

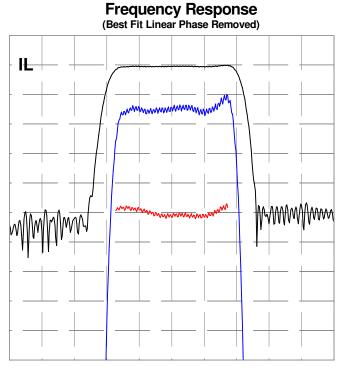
Specifications

| Parameter | Symbol | Min | Typical | Max | Unit |
|----------------------------------|-----------------|------|---------|------|--------------------|
| Center Frequency | Fo | | 300.2 | | MHz |
| Bandwidth | В | | 16 | | MHz |
| -3 dB Bandwidth | B ₃ | 15.2 | 15.4 | | MHz |
| –40 dB Bandwidth | B ₄₀ | | 19.8 | 20 | MHz |
| Delay | To | 1.37 | 1.382 | 1.39 | µsec |
| Insertion Loss | IL | | 21.2 | 22 | dB |
| Amplitude Ripple | | | 0.7 | 1.2 | dB _{P-P} |
| Phase Ripple | | | 4.5 | 6 | deg _{P-P} |
| Rejection | | 46 | 50 | | dB |
| Spurious for $ t - T_0 > .9T_0$ | | | -40 | -39 | dB |
| Substrate Material | X112Y-LT | | | | |

Notes

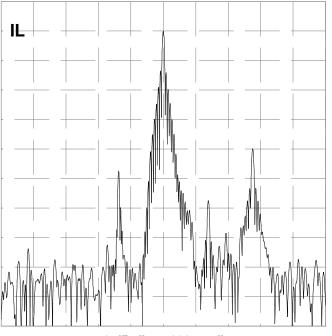
- 1. Center Frequency (F₀) and Bandwidth (B) are defined, not measured.
- 2. Insertion Loss is the minimum loss for $|f F_0| < .5B$
- 3. Ripple spec applies to the $|f F_0| < .4B$, and is doubled for $.4B < |f F_0| < .5B$
- 4. Rejection spec applies to $(B_{40} \text{ Spec} B/2) < |f F_0| < F_0/2$
- 5. Specifications are at 22 °C only. Unit will operate undamaged from -54 °C to 125 °C with shifts dF₀ = $-x^*$ F₀, dT₀ = x^* T₀, where $x = 18E-6^*$ (temperature -22 °C)

Typical Performance



10 dB/div, 1 dB/div, 10 deg/div, 4.000 MHz/div

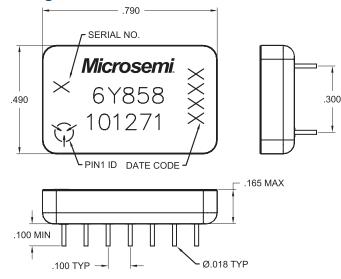
Impulse Response FFT(Frequency Response*Cos(0.5*PI*MIN(1,MAX(0,|f-F0|*2.0/16-1.0)))^2)



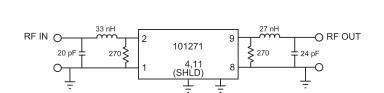
10 dB/div, 1.000 us/div



Package Outline



Matching





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